

Test Description
Test Method

ASTM D 149	Dielectric Breakdown Voltage & Strength 固体电绝缘材料在工频下的介电击穿电压和介电强度
ASTM D 229	Bonding Strength 电气绝缘用刚性薄板及板材的粘合强度
ASTM D 229	Dielectric Constant and Dissipation Factor 电气绝缘用刚性薄板及板材的介电常数和介质损耗
ASTM D 229	Flexural Strength (Lengthwise & Crosswise) 电气绝缘用刚性薄板及板材的弯曲强度
<i>ASTM D 256</i>	<i>Izod Impact Test</i> <i>测定塑料抗艾卓德摆动冲击性</i>
ASTM D 257	DC Resistance of Insulating Materials 绝缘材料的直流电阻或电导率
ASTM D 412	Tensile - Elastomer Properties (Test Method A) 硫化橡胶、热塑橡胶和热塑合成橡胶的拉伸试验法
ASTM D 495	Arc Resistance 固体电气绝缘材料的耐高压小电流电弧性能
ASTM D 570	Water Absorption 塑料吸水率
ASTM D 638	Tensile Properties of Thermoplastic Materials 塑料抗拉特性
<i>ASTM D 648</i>	<i>Deflection Temperature of Polymer Material Under Load</i> <i>在挠曲负荷下塑料边缘位置弯曲温度的标准测试方法</i>
<i>ASTM D 648</i>	<i>Vicat Softening Point of Polymer Materials</i> <i>塑料维卡(Vicat)软化温度的标准试验方法</i>
<i>ASTM D 695</i>	<i>Compressive Strength</i> <i>硬质塑料抗压特性的标准试验方法</i>
ASTM D 790	Flexural Properties of Plastics 未增强和增强塑料及电绝缘材料的挠曲性的标准试验方法
<i>ASTM D 792</i>	<i>Specific Gravity of Polymers</i> <i>用位移法测定塑料密度和比重(相关密度)的标准试验方法</i>
ASTM D 882	Tensile Strength - Thin Polymeric Sheeting (Bias or Machine Direction) 塑料薄板材抗拉特性的标准试验方法
ASTM D 903	Bond Strength Properties of Adhesives - Peel Strength 胶粘剂抗剥落或剥离强度的试验方法
ASTM D 1002	Bond Strength Properties of Adhesives - Lap Shear 用拉力负载法测定单面搭接粘结金属试样的表面剪切强度(金属之间)
<i>ASTM D 1042</i>	<i>Changes in Linear Dimensions of Polymer Materials</i> <i>加速操作状态下塑料线性尺寸变化的标准测试方法</i>
<i>ASTM D 1525</i>	<i>Vicat Softening Point of Polymer Materials</i> <i>塑料维卡(Vicat)软化温度的标准试验方法</i>
ASTM D 1622	Density Determination of Foamed Polymer Material 硬质泡沫塑料表观密度的标准试验方法
<i>ASTM D 1822</i>	<i>Tensile Impact Test</i> <i>测试断裂塑料及电绝缘材料拉伸冲击能量的试验方法</i>
ASTM D 1830	Thermal Endurance of Flex by Curved Electrode 用弧形电极法测定电绝缘挠性薄片材料热稳定性的标准试验方法

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ASTM D 1876	Bond Strength Properties of Adhesives - T-Peel 胶粘剂的抗剥离性的标准试验方法(T型剥离试验)
ASTM D 2095	Bond Strength Properties of Adhesives - Butt Joint 用棒和条状样品测定胶粘剂抗拉强度的标准试验方法
ASTM D 2584	Ignition Loss of Cured Reinforced Resins 固化的增强树脂燃烧损失的标准试验方法
ASTM D 3039	Tensile Properties of Polymer Matrix Composite Materials 聚合母体混合材料抗拉特性的标准试验方法
ASTM D 3045	Heat Aging of Plastics Without Load 无负荷塑料制品热老化的标准实施规程
ASTM D 3165	Strength Properties of Adhesives in Shear by Tension 用单面搭接迭层板装配件的抗拉荷载法测定胶粘剂抗剪切强度的标准试验方法
ASTM D 3386	Coefficient of Linear Thermal Expansion of Electrical Insulating Materials 电绝缘材料的线性热膨胀系数的标准试验方法
ASTM D 3418	Differential Scanning Calorimetry (DSC) 用差示扫描量热法测定聚合物转变温度的标准试验方法
ASTM D 3479	Tension Testing Fatigue of Polymer Matrix Composite Materials 聚合母体混合材料拉伸疲劳度的标准试验方法
ASTM D 3638	Comparative Tracking Index (CTI) 电绝缘材料比较漏电痕迹指数的标准试验方法
ASTM D 3846	In-Plane Shear Strength of Reinforced Plastics 增强塑料的平面剪切强度的标准测试方法
ASTM D 3850	Thermal Gravimetric Analysis (TGA) 用热解重量法测定固体电绝缘材料快速热降解的标准试验方法
ASTM D 3874	Hot Wire Ignition (HWI) 用电热丝法测量材料着火性的标准试验方法
ASTM D 5083	Tensile Properties of Reinforced Thermosetting Plastics 用于直边样品的热增强塑料的拉伸性特性的标准试验方法
ASTM B 193	Resistivity of Electrical Conductor Materials 导体材料电阻率的标准测试方法
ASTM E 8	Tension Testing of Metallic Materials 金属材料拉伸试验的标准试验方法
<i>ASTM E 53</i>	<i>Copper Purity Analysis</i> <i>用重量分析法测定非合金铜中铜含量的标准试验方法</i>
<i>ASTM E 96</i>	<i>Water Vapor Transmission of Materials</i> <i>材料的水蒸气渗透性标准试验方法</i>
ASTM E 345	Tension Testing of Metallic Foils 金属箔的抗拉试验方法
<i>ASTM E 1530</i>	<i>Thermal Conductivity</i> <i>用保护的热流计技术评定材料耐传热性能的标准试验方法</i>
GR-78-CORE	Surface Insulation Resistance (SIR) Telcordia 表面绝缘电阻
IEC 60695-2-11	Glow-Wire Flammability (Ignitability) for End Products 着火危险试验.第2-11部分: 灼热金属线/热线的试验方法.最终产品的灼热金属线可燃性试验方法
IEC 60695-2-12	Glow-Wire Flammability for Materials 材料的灼热丝引燃试验方法

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IEC-60249	Base Materials for Printed Circuits 印制电路用基材
IEC-60326	Specification for Printed Circuits 印制电路规范
IEC-695-10-2	Ball Pressure Test 球压试验
IPC-4101	Specification for Base Materials for Rigid Multilayer Boards 刚性多层印制电路板基材规范
IPC-4103	Specification for Base Materials for High Speed/High Frequency App. 高速/高频设备的基材规范
IPC-6012	Specification for Rigid Printed Boards 刚性印制板的鉴定与性能规范
IPC-6013	Specification for Flexible Printed Boards 挠性印制板的鉴定与性能规范
IPC-6016	Specification for High Density Interconnect (HDI) Layers or Boards 高密度互连层或板的鉴定和性能规范
IPC-6018	Microwave End Product Board Inspection and Test 微波终端产品板的检验和试验规范
IPC-A-600	Acceptability of Printed Boards 印制板的验收条件
IPC-SM-840	Qualification and Performance of Permanent Solder Mask 永久性阻焊剂的鉴定和性能
IPC-TM-650; Method 2.1.1.2	Microsectional Analysis 晶相切片, 半自动晶相切片设备(预备)
IPC-TM-650; Method 2.1.2	Pinhole Evaluation Dye Penetration Method 针孔评定, 干燥渗透法
IPC-TM-650; Method 2.1.5	Surface Examination, Unclad and Metal Clad Material 未覆和覆金属材料表面检查
IPC-TM-650; Method 2.1.6.1	Glass Fabric Weight 纤维布重量
IPC-TM-650; Method 2.1.7	Thread Count 玻璃纤维布线数
IPC-TM-650; Method 2.1.10	Presence of Dicyandiamide Crystals 双氰胺晶体目检
IPC-TM-650; Method 2.1.13	Visual Inspection (Flex) 挠性印制电路材料夹杂物和空洞检验
IPC-TM-650; Method 2.2.1	Mechanical Dimensional Verification 机械结构确认
<i>IPC-TM-650; Method 2.2.4</i>	<i>Dimensional Stability (Flex)</i> <i>挠性电介质材料的结构稳定性</i>
IPC-TM-650; Method 2.2.12	Thickness of Copper by Weight 铜箔厚度—称重法
IPC-TM-650; Method 2.2.12.1	Overall Thickness and Profile Factor of Copper Foils 加工和未加工过的铜箔的全部厚度和外形因数
IPC-TM-650; Method 2.2.12.2	Weight and Thickness of Copper Foils with Releasable Carriers 免搬运铜箔的重量和厚度

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IPC-TM-650; Method 2.2.12.3	Weight and Thickness of Copper Foils with Etchable Carriers 腐蚀性运输下铜箔质量和厚度的确定
IPC-TM-650; Method 2.2.18	Determination of Thickness of Laminates by Mechanical Measurement 层压板厚度机械测量法
IPC-TM-650; Method 2.2.18.1	Determination of Thickness of Metallic Clad Laminates, Cross-sectional 覆金属层压板厚度测定—横截面法
IPC-TM-650; Method 2.3.1.1	Chemical Cleaning of Metal Clad Laminate 化学处理, 材料的相应处理
IPC-TM-650; Method 2.3.1.1	Metal Surfaces Processability 覆金属层压板的化学清洗
IPC-TM-650; Method 2.3.2	Chemical Resistance (Flex) 挠性印制电路材料的耐化学性
IPC-TM-650; Method 2.3.3	Chemical Resistance of Materials 绝缘材料的耐化学性
IPC-TM-650; Method 2.3.4.2	Chemical Resistance of Laminates, Prepreg and Coated Foil Products, by Solvent Exposure 层压板、半固化片和镀层产品的耐化学性—曝露于溶剂中
IPC-TM-650; Method 2.3.4.3	Chemical Resistance 基材的耐化学性—耐二氯甲烷
IPC-TM-650; Method 2.3.6	Etchability 过硫酸铵蚀刻法
IPC-TM-650; Method 2.3.9	Flammability of Prepreg and Thin Laminate 半固化片和薄层压板的燃烧性
IPC-TM-650; Method 2.3.10	Flammability of Laminate 层压板的燃烧性
IPC-TM-650; Method 2.3.10.1	Flammability of Soldermask on Printed Wiring Laminate 印制电路板用阻焊膜的燃烧性
<i>IPC-TM-650; Method 2.3.15</i>	<i>Purity of Copper Foil</i> <i>铜箔或镀层的纯度</i>
IPC-TM-650; Method 2.3.16	Resin Content of Prepreg 半固化片的树脂含量—灼烧法
IPC-TM-650; Method 2.3.16.2	Treated Weight of Prepreg 涂胶半固化片的重量
IPC-TM-650; Method 2.3.17	Resin Flow of Prepreg 半固化片的树脂流动度
IPC-TM-650; Method 2.3.17.1	Resin Flow of Resin Coated Films (Flex) 涂胶膜和无支撑涂胶膜的树脂流动度
IPC-TM-650; Method 2.3.17.2	Resin Flow of "No Flow" Prepreg “不流动”半固化片的树脂流动度
IPC-TM-650; Method 2.3.18	Gel Time of Prepreg 半固化片材料凝胶化时间
IPC-TM-650; Method 2.3.19	Volatile Content of Prepreg 半固化片挥发物含量
IPC-TM-650; Method 2.3.23	Soldermask Cure 热固性阻焊剂的固化(耐久性)
IPC-TM-650; Method 2.3.25	Ionic Cleanliness 表面污染离子的探测和测量

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IPC-TM-650; Method 2.3.37	Volatile Content 介质膜粘结剂的挥发物含量
IPC-TM-650; Method 2.3.38	Surface Organic Contaminant Detection Test 表面有机污染物的探测
IPC-TM-650; Method 2.4.1	Adhesion, Tape Testing 附着力—胶带法
IPC-TM-650; Method 2.4.1.1	Adhesion, Marking Paints and Inks 标记油墨的附着力
IPC-TM-650; Method 2.4.1.5	Treatment Transfer (Treatment Integrity) 迁移处理的测定
IPC-TM-650; Method 2.4.1.6	Adhesion, Polymer Coating 聚合物涂层附着力
<i>IPC-TM-650; Method 2.4.2.1</i>	<i>Flexural Fatigue and Ductility, Foil</i> <i>金属箔的弯曲疲劳和延展性</i>
IPC-TM-650; Method 2.4.3	Flexural Fatigue, Flexible Printed Wiring 挠性印制电路材料的曲挠
<i>IPC-TM-650; Method 2.4.3.1</i>	<i>Flexural Fatigue and Ductility, Flexible Printed Wiring</i> <i>挠性印制电路材料的弯曲疲劳和延展性</i>
IPC-TM-650; Method 2.4.4	Flexural Strength 层压板弯曲强度(室温下)
<i>IPC-TM-650; Method 2.4.4.1</i>	<i>Flexural Strength (At Elevated Temperature)</i> <i>层压板弯曲强度(高温下)</i>
IPC-TM-650; Method 2.4.5	Flexural Endurance 挠性印制电路材料折弯试验
IPC-TM-650; Method 2.4.5	Folding Flexibility 挠性印制电路材料折弯试验
IPC-TM-650; Method 2.4.8	Peel Strength of Metallic Clad Laminates 覆金属层压板剥离强度
IPC-TM-650; Method 2.4.8.1	Peel Strength, Metal Foil (Keyhole Method for Thin Laminates) 金属箔剥离强度(薄层压板锁眼试验)
<u>IPC-TM-650; Method 2.4.8.2</u>	<u>Peel Strength of Metallic Clad Laminates at Elevated Temperature (Hot Fluid Method)</u> 高温下覆金属层压板剥离强度(热液体法)
<i>IPC-TM-650; Method 2.4.8.3</i>	<i>Peel Strength (At Elevated Temperature in Air)</i> <i>高温下覆金属层压板剥离强度(热空气法)</i>
IPC-TM-650; Method 2.4.8.4	Carrier Release, Thin Copper 铜箔的裁存试验
IPC-TM-650; Method 2.4.9	Peel Strength (Flex) 挠性印制电路材料剥离强度
IPC-TM-650; Method 2.4.9.1	Peel Strength of Flexible Circuits - 11/98 挠性电路剥离强度
IPC-TM-650; Method 2.4.12	Solderability, Edge Dip Method 可焊性—边浸法
IPC-TM-650; Method 2.4.13	Solder Float (Flex) 挠性印制电路材料耐浮焊性
IPC-TM-650; Method 2.4.13.1	Thermal Stress of Laminates 层压板热应力试验

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IPC-TM-650; Method 2.4.16	Initiation Tear Strength, Flexible Insulating Materials 挠性绝缘材料初始撕裂强度
IPC-TM-650; Method 2.4.18	Tensile Strength and Elongation @ Elevated Temperature 铜箔的拉伸强度和延伸率
IPC-TM-650; Method 2.4.18.1	Tensile/Elongation/Purity/Ductility 内部镀层拉伸强度和延伸率
IPC-TM-650; Method 2.4.19	Tensile Strength and Elongation, Flexible Printed Wiring Materials 挠性印制电路拉伸强度和延伸率
IPC-TM-650; Method 2.4.21	Bond Strength Test, Unsupported Hole 非支撑孔连接盘粘合强度
IPC-TM-650; Method 2.4.21.1	Bond Strength Test (Surface Mount Lands) 粘合强度—表面贴装盘的垂直拉脱法
IPC-TM-650; Method 2.4.22	Bow & Twist (PCB) 弓曲和扭曲
IPC-TM-650; Method 2.4.22.1	Bow and Twist (Laminate) 层压板的弓曲和扭曲
IPC-TM-650; Method 2.4.24	Thermal Mechanical Analysis (TMA) 玻璃化温度和 Z 向热膨胀—TMA 法
IPC-TM-650; Method 2.4.24.1	Time to Delamination (TMA) 分层时间—TMA 法
IPC-TM-650; Method 2.4.24.3	Glass Transition Temperature of Organic Films 有机膜的玻璃化温度—TMA 法
IPC-TM-650; Method 2.4.24.5	Glass Transition Temperature and Thermal Expansion of Materials Used In High Density Interconnection (HDI) and Microvias -TMA Method 用于 HDI 和微孔材料的玻璃化温度和热膨胀系数—DMA 法
IPC-TM-650; Method 2.4.25	Differential Scanning Calorimetry (DSC) 玻璃化温度和固化因素—DSC 法
IPC-TM-650; Method 2.4.27.2	Solder Mask Abrasion (Pencil Method) 阻焊膜耐摩擦—铅笔法
IPC-TM-650; Method 2.4.28.1	Adhesion, Solder Resist (Mask), Tape Test Method 阻焊膜附着力—胶带法
IPC-TM-650; Method 2.4.29	Adhesion, Solder Mask, Flexible Circuit 挠性电路阻焊膜附着力
IPC-TM-650; Method 2.4.36	Rework Simulation, Plated Through Holes 模拟返工—金属化孔
IPC-TM-650; Method 2.4.38	Scaled Flow of Prepreg 半固化片比例流动度试验
<i>IPC-TM-650; Method 2.4.39</i>	<i>Dimensional Stability of Laminates</i> 玻璃纤维增强薄层压板尺寸稳定性
IPC-TM-650; Method 2.4.42.3	Wire Bond Pull Strength 导线结合拉脱强度
IPC-TM-650; Method 2.5.1	Arc Resistance 印制电路材料的耐电弧
IPC-TM-650; Method 2.5.3	Current Breakdown, Plated Through Holes 镀通孔的耐电流
IPC-TM-650; Method 2.5.4.1	Conductor Temperature Rise Due to Current Changes in Conductors 导线电流变化期间的温度升高

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IPC-TM-650; Method 2.5.5.4

Dielectric Constant and Dissipation Factor of Printed Wiring Board
 Material-Micrometer Method 印制电路板材料的介电常数和介质损耗—测微计法
Dielectric Constant (Permittivity) & Dissipation Factor (Loss Tangent) 1MHz~1.5GHz
 下介电常数和介质损耗—平行板法

IPC-TM-650; Method 2.5.5.9

Dielectric Breakdown

IPC-TM-650; Method 2.5.6

刚性印制电路材料的介质击穿

IPC-TM-650; Method 2.5.6.1

Dielectric Strength, Polymer Solder Mask and/or Conformal Coatings
 聚合阻焊膜和/或保护涂层的介电强度

IPC-TM-650; Method 2.5.6.2

Electric Strength of Printed Wiring Material
 印制电路材料的电气强度

IPC-TM-650; Method 2.5.7

Dielectric Withstanding Voltage (DWV)
 印制板绝缘强度 (DWV) 试验

IPC-TM-650; Method 2.5.7.1

Dielectric Withstanding Voltage - Polymeric Conformal Coating
 电介质耐电压—聚合保护涂层

IPC-TM-650; Method 2.5.14

Resistivity of Copper Foil
 铜箔电阻率

IPC-TM-650; Method 2.5.17

Volume and Surface Resistivity (Flex)
 印制电路材料的体积电阻率和表面电阻

IPC-TM-650; Method 2.5.17.1

Volume and Surface Resistivity
 电介质材料的体积电阻率和表面电阻率

IPC-TM-650; Method 2.5.17.2

Volume Resistivity of Conductive Resistance Used in High Density Interconnection
 (HDI) and Microvias, Two-Wire Method
 HDI 和微孔板用传导材料的体积电阻率—双导线法

IPC-TM-650; Method 2.5.27

Surface Insulation Resistance test
 半成品印制电路材料的表面绝缘电阻

IPC-TM-650; Method 2.6.1

Fungus Resistance (Non-Nutrient)
 印制电路材料的耐霉菌试验

IPC-TM-650; Method 2.6.2

Moisture Absorption, Flexible Printed Wiring
 挠性印制电路吸湿性试验

IPC-TM-650; Method 2.6.3

Moisture and Insulation Resistance
 印制板的吸湿性和绝缘电阻

IPC-TM-650; Method 2.6.3.1

Moisture and Insulation Resistance - Solder Mask
 阻焊膜的吸湿性和绝缘电阻

IPC-TM-650; Method 2.6.3.2

Moisture and Insulation Resistance, Flexible Base Dielectric
 挠性绝缘基材的吸湿性和绝缘电阻

IPC-TM-650; Method 2.6.3.3

Surface Insulation Resistance (SIR)
 表面绝缘电阻, 溶剂

IPC-TM-650; Method 2.6.3.4

Moisture and Insulation Resistance – Conformal Coating
 绝缘保护涂层的吸湿性和绝缘电阻

IPC-TM-650; Method 2.6.3.5

Bare Board Cleanliness by Surface Insulation Resistance
 用表面绝缘电阻测定裸板清洁度

IPC-TM-650; Method 2.6.3.6

Surface Insulation Resistance - Fluxes – Telecommunications
 表面绝缘电阻—微电流法

IPC-TM-650; Method 2.6.5

Physical Shock, Multilayer Printed Wiring
 多层印制板的物理冲击

IPC-TM-650; Method 2.6.6

Temperature Cycling, Printed Wiring Board
 印制电路板的温度循环

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IPC-TM-650; Method 2.6.7	Thermal Shock and Continuity, Printed Board 印制板的热冲击和连续性
IPC-TM-650; Method 2.6.7.1	Thermal Shock--Polymer Solder Mask Coatings 绝缘保护涂层的热冲击
IPC-TM-650; Method 2.6.7.2	Thermal Shock, Continuity and Microsection, Printed Board 印制板的热冲击、连续性和晶相切片
IPC-TM-650; Method 2.6.7.3	Thermal Shock - Soldermask 阻焊膜的热冲击
IPC-TM-650; Method 2.6.8	Thermal Stress, Plated Through-Holes 镀通孔的热应力试验
IPC-TM-650; Method 2.6.8.1	Thermal Stress, Laminate 层压板的热应力试验
<u>IPC-TM-650; Method 2.6.9</u>	<u>Vibration, Rigid Printed Wiring</u> 刚性印制电路的振动试验
IPC-TM-650; Method 2.6.11	Hydrolytic Stability/Aging 阻焊膜的水解稳定性
IPC-TM-650; Method 2.6.14	Resistance to Electrochemical Migration, Solder Mask 耐电迁移——阻焊膜
IPC-TM-650; Method 2.6.14.1	Electrochemical Migration Resistance Test 耐电迁移试验
IPC-TM-650; Method 2.6.16	Pressure Vessel Thermal Stress 环氧玻璃布层压板完整性——压力容器法
IPC-TM-650; Method 2.6.21	Service Temperature of Flexible Printed Wiring 挠性印制电路的工作温度
IPC-TM-650; Method 2.6.25	Conductive Anodic Filament Test (CAF) 阳极丝传导试验 (CAF)
J-STD-001	Requirements for Soldered Electrical and Electronic Assemblies 电子装配和电气焊接要求
J-STD-002	Solderability Tests for Component Leads, Terminations, and Wires 起断、终端和金属线结构的可焊性试验
J-STD-003	Solderability Tests for Printed Boards 印制板可焊性试验
<i>MIL-P-50884</i>	<i>Printed Wiring Boards, Flexible or Rigid-Flex</i> <i>挠性和刚-挠性印制线路板</i>
<i>MIL-P-55110</i>	<i>Printed Wiring Boards, Rigid</i> <i>刚性印制线路板</i>
<i>MIL-PRF-31032</i>	<i>Printed Wiring/Circuit Board Performance Specification</i> <i>印制线路/电路板性能规范</i>
<i>MIL-PRF-50884</i>	<i>Printed Wiring Boards, Flexible or Rigid-Flex</i> <i>挠性或刚-挠性印制线路板</i>
<i>MIL-PRF-55110</i>	<i>Printed Wiring Boards, Rigid</i> <i>刚性印制线路板</i>
<i>MIL-STD-1130</i>	<i>Wirewrap Bit Certification</i> <i>导线卷绕位的验证</i>
UL 746A	Polymeric Materials - Short Term Properties 聚合物材料——短时性能评定

Test Description

Test Method

UL 746B	Polymeric Materials - Long Term Property Evaluations 聚合物材料——长时性能评定
UL 746C	Polymeric Materials - Use in Electronic Equipment Evaluations 电气设备用聚合物材料的评定
UL 746D	Polymeric Materials - Fabricated Parts 聚合物材料——成品零部件
UL 746E	Polymeric Materials - Industrial Laminates and Materials 聚合材料——工业用层压板、纤维缠绕管、硬化纸板及印制线路板用材料
UL 796	Printed Wiring Boards 印制线路板
UL 796F	Flexible Materials Interconnect Constructions 挠性材料互连结构
UL 94	Tests for Flammability of Plastic Materials 各种电气装置和设备中零部件用塑料材料燃烧性试验
<i>WS-6536</i>	<i>Tensile/Elongation/Purity/Ductility</i> <i>拉伸/延伸/纯度/延展性</i>